ON Semiconductor

Is Now



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2-Bit Bus Switch

The 7WB3125 is an advanced high-speed low-power 2-bit bus switch in ultra-small footprints.

Features

- High Speed: $t_{PD} = 0.25 \text{ ns (Max)} @ V_{CC} = 4.5 \text{ V}$
- 3 Ω Switch Connection Between 2 Ports
- Power Down Protection Provided on Inputs
- Zero Bounce
- TTL-Compatible Control Inputs
- Ultra-Small Pb-Free Packages
- These are Pb-Free Devices



ON Semiconductor®

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MARKING DIAGRAMS



UDFN8 MU SUFFIX CASE 517AJ





Micro8[™] DM SUFFIX CASE 846A





UDFN8 1.95 x 1.0 CASE 517CA



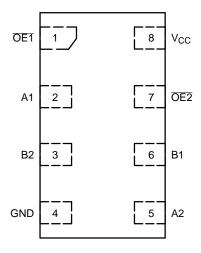
A = Assembly Location

Y = Year
W = Work Week
M = Date Code
■ Pb-Free Package

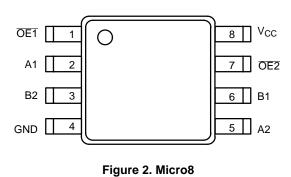
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.



(Top Thru-View)



(Top View)

Figure 1. UDFN8

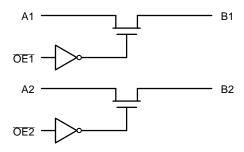


Figure 3. Logic Diagram

FUNCTION TABLE

Input OEn	Function		
L	Bn = An		
Н	Disconnect		

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{IN}	Control Pin Input Voltage	-0.5 to +7.0	V
V _{I/O}	Switch Input / Output Voltage	-0.5 to +7.0	V
I _{IK}	Control Pin DC Input Diode Current V _{IN} < GND	-50	mA
I _{OK}	Switch I/O Port DC Diode Current V _{I/O} < GND	-50	mA
Io	ON-State Switch Current	± 128	mA
	Continuous Current Through V _{CC} or GND	± 150	mA
I _{CC}	DC Supply Current Per Supply Pin	± 150	mA
I _{GND}	DC Ground Current per Ground Pin	± 150	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	150	°C
$\theta_{\sf JA}$	Thermal Resistance UDFN8 (Note 1) Micro8	111 392	°C/W
P _D	Power Dissipation in Still Air at 85°C UDFN8 Micro8	1127 319	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Mode (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125°C (Note 5)	±200	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
- 2. Tested to EIA / JESD22-A114-A.
- 3. Tested to EIA / JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	Positive DC Supply Voltage	4.0	5.5	V	
V_{IN}	Control Pin Input Voltage	0	5.5	V	
V _{I/O}	Switch Input / Output Voltage	0	5.5	V	
T _A	Operating Free-Air Temperature			+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate	Control Input Switch I/O	0 0	5 DC	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

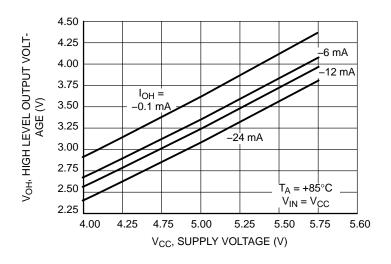
			V _{CC}	T _A = 25°C			T _A = -55°C to +125°C		
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Unit
V _{IK}	Clamp Diode Voltage	$I_{I/O} = -18 \text{ mA}$	4.5			-1.2		-1.2	V
V _{IH}	High-Level Input Voltage (Control)		4.0 to 5.5	2.0			2.0		V
V _{IL}	Low-Level Input Voltage (Control)		4.0 to 5.5			0.8		0.8	V
V _{OH}	Output Voltage High	See Figure 4							
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5 ± 0.1		± 0.1		±1.0	μΑ	
I _{OFF}	Power Off Leakage Current	$V_{I/O} = 0 \text{ to } 5.5 \text{ V}$	0			±0.1		±1.0	μΑ
lcc	Quiescent Supply Current	$I_O = 0$, $V_{IN} = V_{CC}$ or 0 V	5.5			± 0.1		±1.0	μΑ
Δl _{CC}	Increase in Supply Current (Control Pin)	One input at 3.4 V; Other inputs at V _{CC} or GND	uts at					2.5	mA
R _{ON}	Switch ON Resistance	V _{I/O} = 0, I _{I/O} = 64 mA I _{I/O} = 30 mA	4.5		3 3	7 7		7 7	Ω
		V _{I/O} = 2.4, I _{I/O} = 15 mA			6	15		15	
		V _{I/O} = 2.4, I _{I/O} = 15 mA	4.0		10	20		20	

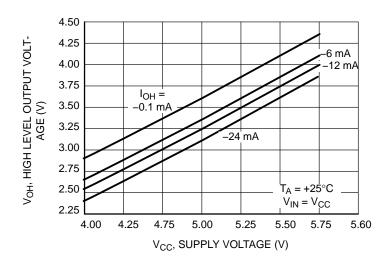
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25 °C		T _A = -55°C to +125°C			
Symbol	Parameter	Test Condition	(V)	Min	Тур	Max	Min	Max	Unit
t _{PD}	Propagation Delay, Bus to Bus	See Figure 5	4.0 to 5.5			0.25		0.25	ns
t _{EN}	Output Enable Time	See Figure 5	4.5 to 5.5	0.8	2.5	4.2	0.8	4.2	ns
			4.0	0.8	3.0	4.6	0.8	4.6	
t _{DIS}	Output Disable Time		4.5 to 5.5	0.8	3.0	4.8	0.8	4.8	ns
			4.0	0.8	2.9	4.4	0.8	4.4	
C _{IN}	Control Input Capacitance	V _{IN} = 5 or 0 V	5.0		2.5				pF
C _{IO(ON)}	Switch On Capacitance	Switch ON	5.0		10				pF
C _{IO(OFF)}	Switch Off Capacitance	Switch OFF	5.0		5				pF

TYPICAL DC CHARACTERISTICS





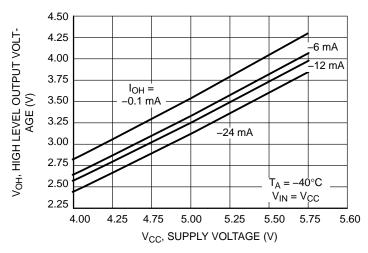
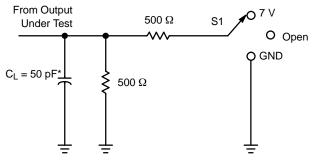


Figure 4. Output Voltage High vs Supply Voltage

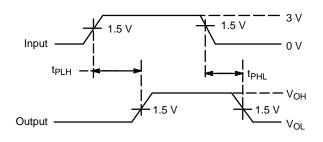
AC LOADING AND WAVEFORMS

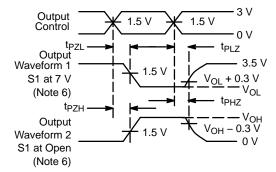
Parameter Measurement Information



Test	S 1
t _{PD}	Open
t _{PLZ} /t _{PZL}	7 V
t _{PHZ} /t _{PZH}	Open

^{*}C_L includes probes and jig capacitance.





Voltage Waveforms Propagation Delay Times

Voltage Waveforms Enable and Disable Times

- 6. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control
- 7. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns. 8. The outputs are measured one at a time, with one transition per measurement.
- 9. t_{PLZ} and t_{PHZ} are the same as t_{DIS}.
- 10. t_{PZL} and t_{PZH} are the same as t_{EN}.
 11. t_{PHL} and t_{PLH} are the same as t_{PD}.

Figure 5. t_{PD}, t_{EN}, t_{DIS} Loading and Waveforms

ORDERING INFORMATION

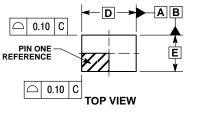
Device	Package	Shipping [†]
7WB3125MUTAG	UDFN8 (Pb-Free)	3000 / Tape & Reel
7WB3125DMR2G	Micro8 (Pb-Free)	4000 / Tape & Reel
7WB3125DMUTCG	UDFN8, 1.95 x 1.0, 0.5 mm Pitch (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

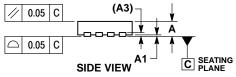
PACKAGE DIMENSIONS

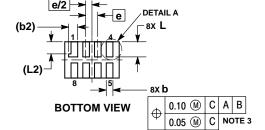
UDFN8 1.8 x 1.2, 0.4P

CASE 517AJ **ISSUE O**





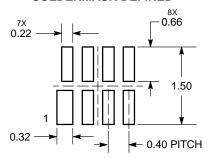




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
 4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE, FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
 5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

	MILLIMETERS						
DIM	MIN	MAX					
Α	0.45	0.55					
A1	0.00	0.05					
A3	0.127	REF					
b	0.15	0.25					
b2	0.30	REF					
D	1.80	BSC					
Е	1.20	BSC					
е	0.40	BSC					
L	0.45 0.55						
L1	0.00 0.03						
L2	0.40 REF						

MOUNTING FOOTPRINT* SOLDERMASK DEFINED

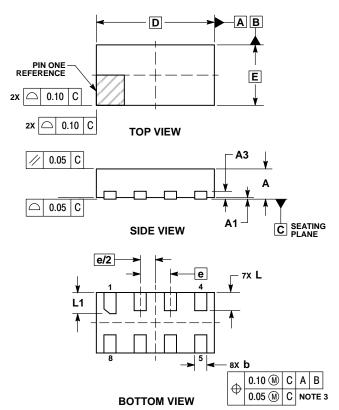


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN8 1.95x1.0, 0.5P CASE 517CA ISSUE O



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

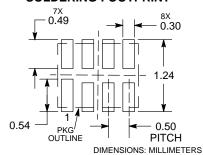
 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.

 4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A3	0.13	REF				
b	0.15	0.25				
D	1.95	BSC				
E	1.00	BSC				
е	0.50 BSC					
L	0.25 0.35					
11	0.30 0.40					

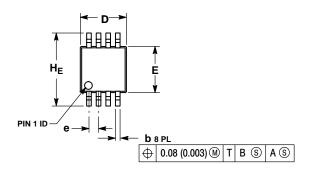
RECOMMENDED SOLDERING FOOTPRINT*

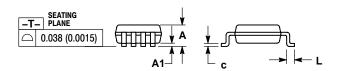


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

Micro8™ CASE 846A **ISSUE H**





NOTES:

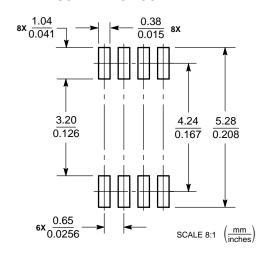
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- DIMENSIONING MULT OLD ANY UNITED ANY UNITED AND THE JOB J. 1992.

 CONTROLLING DIMENSION: MILLIMETER.

 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 846A-01 OBSOLETE, NEW STANDARD 846A-02.

	MILLIMETERS			MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX			
Α			1.10		1	0.043			
A1	0.05	0.08	0.15	0.002	0.003	0.006			
b	0.25	0.33	0.40	0.010	0.013	0.016			
С	0.13	0.18	0.23	0.005	0.007	0.009			
D	2.90	3.00	3.10	0.114	0.118	0.122			
E	2.90	3.00	3.10	0.114	0.118	0.122			
е		0.65 BSC		0.026 BSC					
L	0.40	0.55	0.70	0.016	0.021	0.028			
HE	4.75	4.90	5.05	0.187	0.193	0.199			

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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